

LNPT[™] THERMOCOMP[™] COMPOUND RB004

RB-1004

REGION AMERICAS

DESCRIPTION

LNP THERMOCOMP RB004 compound is based on Nylon 6/6 resin containing 20% glass bead.

GENERAL INFORMATION	
Features	Low Warpage, High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Bead
Polymer Types	Polyamide 66 (Nylon 66)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, brk, Type I, 5 mm/min	80	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	3.7	%	ASTM D638
Tensile Modulus, 50 mm/min	4100	MPa	ASTM D638
Flexural Modulus, 1.3 mm/min, 50 mm span	3870	MPa	ASTM D790
Tensile Stress, yield, 5 mm/min	79	MPa	ISO 527
Tensile Stress, break, 5 mm/min	75	MPa	ISO 527
Tensile Strain, yield, 5 mm/min	3.8	%	ISO 527
Tensile Strain, break, 5 mm/min	3.9	%	ISO 527
Tensile Modulus, 1 mm/min	4150	MPa	ISO 527
Flexural Stress	119	MPa	ISO 178
Flexural Modulus, 2 mm/min	3700	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	227	J/m	ASTM D4812
Izod Impact, notched, 23°C	28	J/m	ASTM D256
Instrumented Dart Impact Total Energy, 23°C	2	J	ASTM D3763
Izod Impact, unnotched 80°10°4 +23°C	16	kJ/m ²	ISO 180/1U
Izod Impact, notched 80°10°4 +23°C	4	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 0.45 MPa, 3.2 mm, unannealed	233	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	81	°C	ASTM D648

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -30°C to 30°C, flow	7.3E-05	1/°C	ASTM D696
CTE, -30°C to 30°C, xflow	7.1E-05	1/°C	ASTM D696
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	219	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	77	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Specific Gravity	1.29	-	ASTM D792
Density	1.28	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.62	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1 – 3	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1 – 3	%	ASTM D955
Moisture Absorption (23°C / 50% RH)	1.1	%	ISO 62
INJECTION MOLDING ⁽³⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.15 – 0.25	%	
Melt Temperature	280 – 305	°C	
Front - Zone 3 Temperature	295 – 305	°C	
Middle - Zone 2 Temperature	280 – 295	°C	
Rear - Zone 1 Temperature	265 – 275	°C	
Mold Temperature	95 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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